

Docket No.: 50090-306

## UTILITY PATENT APPLICATION UNDER 37 CFR 1.53(b)



Box PATENT APPLICATION Commissioner for Patents Washington, DC 20231 Sir:

Transmitted herewith for filing is the patent application of:

INVENTOR: Hiroshi TOBIMATSU, Yuuki KAMIURA, Seiji OKURA, Mahito

**SAWADA** 

FOR: METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE HAVING

PASSIVATION FILM AND BUFFER COATING FILM

Enclose	ed are:				
$\Box$	10 pages of specification, claims, abstract.				
$\overline{}$	Declaration and Power of Attorney.				
$\Box$	Priority Claimed.				
	Certified copy of Japanese Patent Application No. 2001-000408				
oxdot	3 sheets of formal drawing.				
	An assignment of the invention to Mitsubishi Denki Kabushiki Kaisha and Ryoden				
	Semiconductor System Engineering Corporation				
	and the assignment recordation fee.				
	An associate power of attorney.				
	A verified statement to establish small entity status under 37 CFR 1.9 and 37 CFR 1.27.				
	Information Disclosure Statement, Form PTO-1449 and reference.				
$[\cdot]$	Return Receipt Postcard				

The filing fee has been calculated as shown below:

	NO. OF CLAIMS		EXTRA CLAIMS	RATE	AMOUNT
	CLAIMS		CLAIMS	KATL :	AWIOC.WI
Total Claims	6	-20	0	\$18.00	\$0.00
Independent Claims	1	-3	0	\$80.00	\$0.00
	Multiple Dependent Claim(s)				
				Basic Fee	\$710.00
	Total of Above Calculations				\$710.00
	Less ½ for Small Entity				
Assignment & Recording Fee			\$40.00		
				Total Fee	\$750.00



	Please charge my Deposit Account No. 500417 in the amount of \$750.00. A duplicate copy of this sheet is enclosed.  The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 500417. A duplicate copy is enclosed.  Any additional filing fees required under 37 CFR 1.16.				
•	The Commissioner is hereby authorized to charge payment of the following fees during the pendency of this application or credit any overpayment to Deposit Account No. 500417. A duplicate copy of this sheet is enclosed.  Any patent application processing fees under 37 CFR 1.17.  Any filing fees under 37 CFR 1.16 for presentation of extra claims.				
	Respectfully submitted,				
	MCDERMOTT, WILL & EMERY				
	to the second of				
	Stephen A. Becker				
	Registration No. 26,527				
	3 <sup>th</sup> Street, N.W.				

Washington, DC 20005-3096 (202) 756-8000 SAB:prp **Date: July 24, 2001** Facsimile: (202) 756-8087